

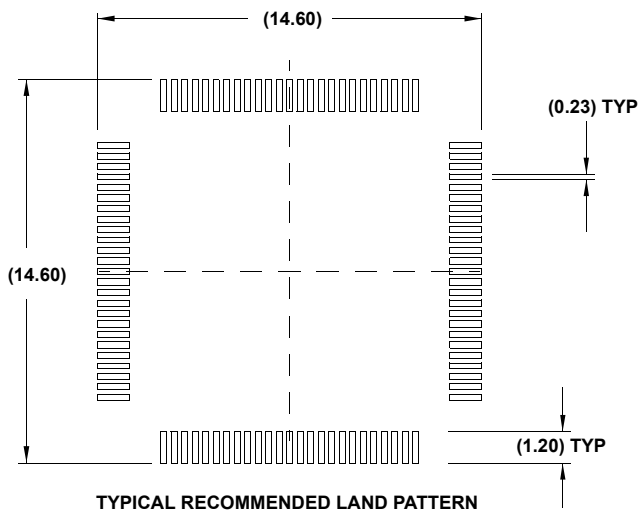
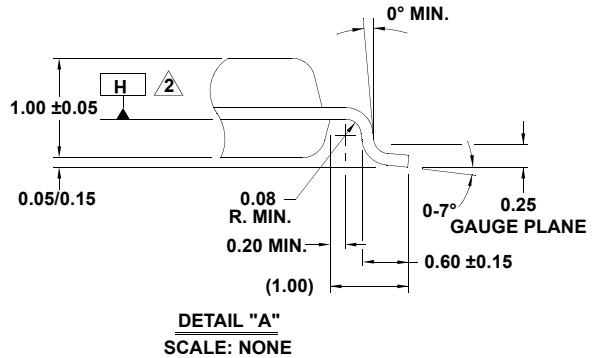
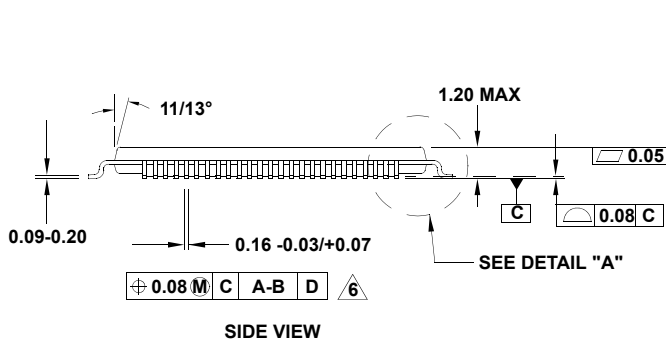
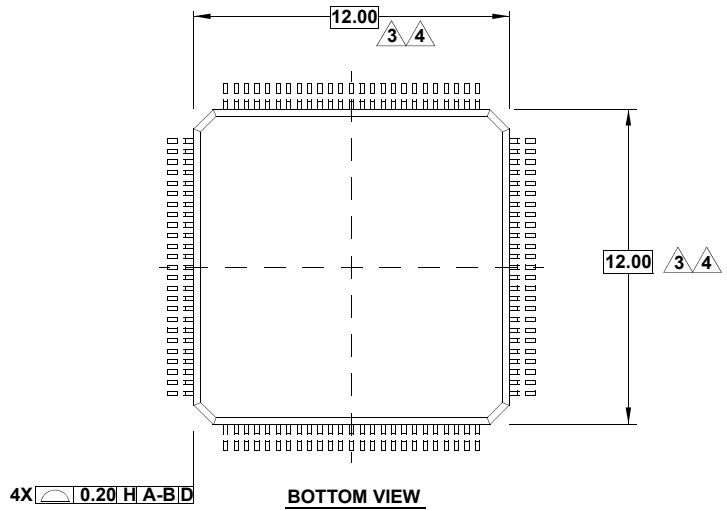
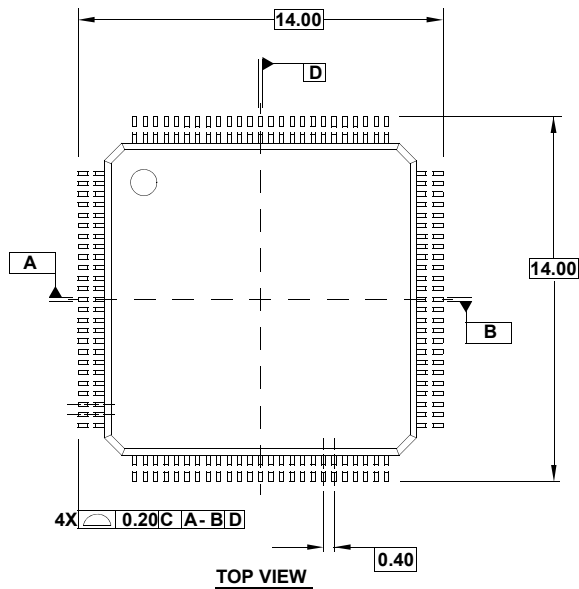
Plastic Packages for Integrated Circuits

Package Outline Drawing

Q100.12x12A

100 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE (TQFP)

Rev 0, 2/11



NOTES:

- All dimensioning and tolerancing conform to ANSI Y14.5-1982.
- Datum plane **H** located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- Dimensions do not include mold protrusion. Allowable mold protrusion is 0.25mm per side.
- These dimensions to be determined at datum plane **H**.
- Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
- Dimension does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total at maximum material condition. Dambar cannot be located on the lower radius or the foot.
- Controlling dimension: millimeter.
- This outline conforms to JEDEC publication 95 registration MS-026, variation ADE.
- Dimensions in () are for reference only.